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(54) **Method for making a multilayered circuitized substrate**

(57) A method of making a multilayered circuitized substrate (101) in which a continuous process is used to form electrically conductive layers (65) which each will form part of a sub-composite (75, 75', 75''). The sub-composites (75, 75', 75'') are then aligned such that openings (57) within the conductive layers (65) are also

aligned, the sub-composites (75, 75', 75'') are then bonded together, and a plurality of holes (113) are then laser drilled through the entire thickness of the bonded structure. The dielectric layers (67, 69) used in the sub-composites (75, 75', 75'') do not include continuous or semi-continuous fibers therein, thus expediting hole formation there-through.

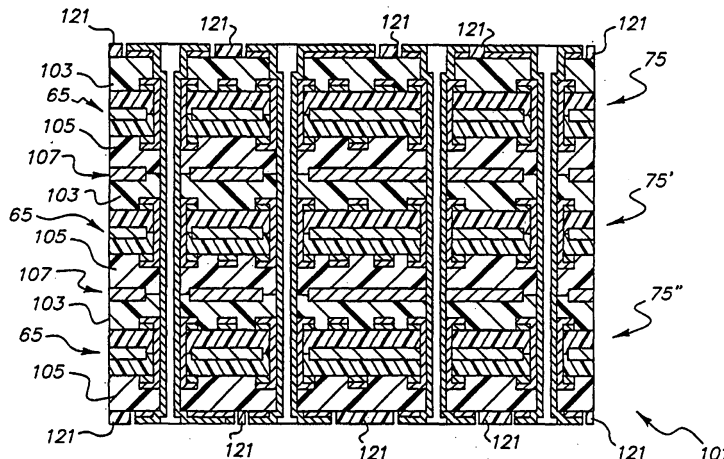


FIG. 11

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EUROPEAN SEARCH REPORT

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The present search report has been drawn up for all claims			
Place of search Munich		Date of completion of the search 30 September 2010	Examiner Kelly, Derek
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**ANNEX TO THE EUROPEAN SEARCH REPORT
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